

Component List

Bill of Materials For Project [300-S6_FMC.PrjPcb] (No PCB Document Selected)



Source Data: 300-S6_FMC.PrjPcb
 Project: 300-S6_FMC.PrjPcb
 Variant: None

Report Date: 5/12/2014 5:40:01 PM
 Print Date: 5/30/2014 3:12:09 PM

#	Quantity	Designator	Description	MFG	MFGPN	Footprint	Value	DNP	Size	Watt	Cost	Availability	Size mm	Power W	Cost	Received
1	4	B1, B2, B3, B4	Single Terminal Socket	NA	NA	MTG300_600	NA		25	0	0	NA	100	0	0	NA
2	72	C6, C7, C9, C11,	Ceramic Chip Capacitor 0201 0.22uF 6.3V 20% X5R	TY	JMK063BJ224MP-F		0.22uF		.5	0	.04	150K-AV	36	0	2.88	0
3	13	C55, C62, C74,	Ceramic Chip Capacitor 1206 100uF 6.3V 20% X5R	MUR	GRM31CR60J107ME39L		100uF		20	0	1.18	150K-AV	260	0	15.34	0
4	19	C39, C40, C46,	Ceramic Chip Capacitor 0402 4.7uF 6.3V 20% X5R	Samsung	CL05A475MQ5NRNC		4.7 uF		1.9	0	.03	930K-AV	36.1	0	0.57	0
5	1	C91	Ceramic Chip Capacitor 0402 0.22uF 6.3V 10% X5R	AXI	04026D224KAT2A		0.22uF		1.2	0	.004	2M-AV	1.2	0	0.004	0
6	4	C109	CAP CER 0.022UF 10V 10% X5R 0201	TY	LMK063BJ223KP-F		0.022uF		.5	0	.02	150K-AV	2	0	0.08	0
7	1	CBL	White miniSAS 8i 68 ctkts	3M	8F68-AAG105-1.00		68ctkt		0	0	26.66	100-DK	0	0	26.66	6
8	2	D1, D4	PolyZen Polymer Protected Zener Diode 5.6V 2.3A	TE	ZEN056V230A24LS	PolyZen	5.6V 2.3A		16	.120	.47	6K-AV	32	0.24	0.94	0
9	2	D2, D3	DFLS130L-7 in a PowerDI_123 Vfs-3	Diodes Inc	DFLS130L-7	PowerDI_123	.2Vf		7.41	0.5	.13	10K-AV	14.82	1	0.26	0
10	4	D5, D6, D15, D17	LED, Red, LTST-C190CKT	LTP	LTST-C190CKT	LED_LITE-LTST-C191TBKT-2	Red		.136	.018	.02	9K-AV	0.544	0.072	0.08	0
11	6	D11, D12	LED, GRN, LGL29K-G2J1-24-Z, 0603	OSRAM	LGL29K-G2J1-24-Z	LED_LITE-LTST-C191TBKT-2	Green		.136	.034	.21	5K-AV	0.816	0.204	1.26	0
12	1	D13	Yellow LED	LTP	LTST-C190CKT	LED_LITE-LTST-C191TBKT-2	Red		.136	.018	.02	9K-AV	0.136	0.018	0.02	0
13	1	D14	Silicon Switching Diode for High-Speed Switching	INF	BAS16	SOT-23	25W		7.25	.025	.07	8K-DK	7.25	0.025	0.07	0
14	1	D16	Blue LED Vf=2.7V 0603 SMD	LTP	LTST-C190CKT	LED_LITE-LTST-C191TBKT-2	Red		.136	.018	.02	9K-AV	0.136	0.018	0.02	0
15	1	IC1	1.7-5.5V 64K 12C Serial EEPROM	TECHNOLOGY	24AA64T-I/MC	S175X155	64K		15	0.0165	.43	151K-AV	15	0.0165	0.43	0
16	1	J1	Connector VITA 57, 400 Male contacts in 10 row abcdefghj	MOLEX	45970-4315	SAMTEC ASP-134488-01	NA		820	0	22.91	215-AV	820	0	22.91	6
17	5	J2, J3, J8, J10, J11	SD-75783-001	MOLEX	75783-0326	CON_MLX-75783-001 - composite	NA		690	0	6.10	CALL	3450	0	30.5	0
18	4	J4, J5, J6, J7	Connector HDMI 19 Male + 1 Shield	MOLEX	46765-1001	CON_MLX-0467651001	20 ckt		48.75	0	1.34	4000-AV	195	0	5.36	0
19	1	J9	2.0mm 7x2 shrouded header	MOLEX	87832-1420	CON_MLX-87332-1420-2	14cct		104.90	0	2	39K-AV	104.9	0	2	0
20	1	J12	HEADER,4PIN,MALE,.256 PITCH,STRAIGHT	Amp/Tyco	640445-4	CON_TE-640445-4	4 ckt		120	0	.45	188K-AV	120	0	0.45	0
21	8	L6, L7, L8	FB SM 220 ohm@100MHz 2000mA 0.25 0.045 ohm@DC L0805	MUR	BLM21PG221SN1D	L0805	220 ohm		5.42	.05	.04	200K-AV	43.36	0.4	0.32	0
22	2	P1, P2	Header, 2-Pin	TE	102972-2	HDR1X2	2cct		10	0	.13	10K-Mou	20	0	0.26	0
23	1	P3	Header, 20-Pin, Dual row	Gravitech	20M2-254mm	HDR2X20-2	2x20		350	0	1.68	61-Mou	350	0	1.68	0
24	0	PCB1	PCB Layout \$4990.00 / 10 Boards	U of A Physics	0300-S6_FMC_Layout		NA		0	0	499	10 days	0	0	0	0
25	0	PCB2	PCB Manufacture \$4349.80 / 10 Boards	U of A Physics	0300-S6_FMC_PCB		NA		0	0	434.98	10 days	0	0	0	0
26	0	PCB3	PCB Assemble \$3137.35 / 5 Boards	U of A Physics	0300-S6_FMC_PCB		NA		0	0	627.47	10 days	0	0	0	0
27	1	PS1	2.5V 1.3A LDO Reg DFN6	ST	ST1L05PU25	DFN6D_127P600-8N	2.5V 1.3A LDO Reg DNF6		9	.05	.96	1200-Mouser	9	0.05	0.96	0
28	2	PS2, PS3	Adjustable1.1A Single Resistor Low Dropout Regulator	LTC	LT3080EDD#TRPBF	ik380			9	.03	4.36	5K-dk	18	0.06	8.72	0
29	7	Q5, Q6, Q7	N-Channel MOSFET	Diodes Inc	DMG1012T-SOT523	SOT-23_N	20V		4	0.01	.03	450K-AV	28	0.07	0.21	0
30	25	R44, R45, R46,	RES SM 100 62mW 0.01 R0402	DALE	CRCW0402100RFKED	RESC_0402	100		1.9	0.062	.01	1M-AV	47.5	1.55	0.25	0
31	15	R17, R18, R20,	RES 0402 4K87 1/16W	DALE	CRCW04024K87FKED	RESC_0402	4K87		1.9	0.001	.01	1M-AV	28.5	0.015	0.15	0
32	2	R4, R34	RES 0402 2K4 1/16W	DALE	CRCW04022K40FKED	RESC_0402	2K4		1.9	0.001	.01	1M-AV	3.8	0.002	0.02	0
33	1	R5	RES SM 22.0 62mW 0.01 R0402	DALE	CRCW040222R0FKED	RESC_0402	22R0		1.9	0.062	.01	1M-AV	1.9	0.062	0.01	0
34	5	R27	RES SM 0R0 62mW 0.01 R0402	DALE	CRCW0402000020ED	RESC_0402	0R0		1.9	0.062	.01	1M-AV	9.5	0.31	0.05	0
35	2	R7, R8	RES 0402 1K 1/16W	DALE	CRCW04021K00FKED	RESC_0402	1K		1.9	0.001	.01	15K-AV	3.8	0.002	0.02	0
36	3	R9, R10, R12	RES 0402 100K 1/16W 1%	DALE	CRCW0402100KFKED	RESC_0402	100K		1.9	0	.01	1M-AV	5.7	0	0.03	0
37	1	R11	RES 0402 120K 1/16W 1%	DALE	CRCW0402120KFKED	RESC_0402	120K		1.9	0	.01	1M-AV	1.9	0	0.01	0
38	4	R29, R38, R56, R68	RES SM 150 62mW 0.01 R0402	DALE	CRCW0402150RFKED	RESC_0402	150		1.9	0.062	.01	1M-AV	7.6	0.248	0.04	0
39	7	R35, R36, R37, R64	RES SM 300 62mW 0.01 R0402	DALE	CRCW0402300RFKED	RESC_0402	300		1.9	0.062	.01	1M-AV	13.3	0.434	0.07	0
40	4	R39, R43, R67, R69	RES 0402 1M 1/16W 1%	DALE	CRCW04021M00FKED	RESC_0402	1M		1.9	0	.01	1M-AV	7.6	0	0.04	0
41	1	RP1	4-Resistor Array 3.2x1.6mm	Bourns	CAY16-472J4LF	RP4K4LCC-2	4.7K ohm		5.12	0.001	.14	23K-Mou	5.12	0.001	0.14	0
42	1	SW1	SW_PB_SPST_4POS_SMT	NKK	HP03154FKP2-R	SW_PB_SPST_4POS_SMT	3VA Nch		36	0	.65	1300-Mou	36	0	0.65	0
43	1	U1	FPGA-XSP6-XC6SLX100-GA676	XLX	XC6SLX100-2FG676C	FG676	XC6SLX100-2FG676C		729	6	146.36	25-AV	729	6	146.36	0
44	2	U2, U3	4-bit non-inverting translator 1.2 V to 5 V.	TI	TXB0104RUT	RUT-N12_OFN127P600-8N	TXB0104RUT		4	0	.75	1200-AV	8	0	1.5	0
45	1	U4	128Mbit SPI NOR in SO8W	Micron	N25Q128A13BSE40F	SO8W	128K		56	0.066	3.20	370-AV	56	0.066	3.2	0
46	1	X1	Osc SM LVDS 200MHz DSC1123 / Si530 LVDS OSC	Abracon/Micron	DSC1123D12-200.0000T	XTAL_Si530	200MHz		35	0.150	2.5	4 Wk Lead-Mou	35	0.15	2.5	0
Approved													6664.482	11.0135	277.02	
Notes																

ref: INV_012314A

Jan 23 2014

to: **University of Arizona**
(Physics Dept – HEPP Group)
1118 E 4th Street, PAS 81 Room 444,
Tucson, Arizona
USA - 85719

remit payment to: **OnGrid Design Inc**

22 Valleybrae Court,
Caledon, Ontario
Canada - L7C 1B8

attn: Vivian Knight

contact: Glenn Rutherford

item	description	purchase order	item charge
1	PCB design of Spartan_6 - FMC Rev_A (300_S6_FMC)	n/a	\$4990.00
2			
3			
4			
5			

NOTE: all items are due within 30 days of receipt of this invoice

tax	-
total	\$4990.00

Currency - **USA**

Attention: Bill Hart
UNIVERSITY OF ARIZONA - OSIRIS
billhart@email.arizona.edu



Viasystems Sales, Inc.
3140 E. Coronado Street
Anaheim, CA 92806, USA
www.viasystems.com

Date: 03/28/2014

Part Number: S6_FMC Rev: -
Part Description:

QUOTATION
Offer to Sell

Build Site: Denver, CO
Quotation No. D47874.0
Customer Code: ARIZONAU
DCN: 0

Applicable Notes:
Incoterm: Ex Works
Named Place: Viasystems Dock
Payment Terms: 45 Days

Piece Price	10 Days	15 Days
10	294.98	256.50
50	121.10	105.30
100	90.85	79.00

Prices in : USD

Unless otherwise specified, all pricing is per individual part.

Tooling Charges

NRE: 1050.00
E-Test: 350.00
AS9102 FA: N/A.00

Part Description:

Layers: 14L	Part Size: 3.996x2.716	Finish: Immersion Gold	Copper Outer: 0.5
Material: 370HR	Array: 0x0 - 0	Other Finishes: None	Copper Inner: 0.5
Thickness: 0.062	Hole Count: 1763	Other Finishes: None	Impedance: YES
Specification: 6012-2	Smallest Hole: 0.008	EAU: N/A	MOQ: N/A

Adjacency Testing may be performed on Class 3 products unless otherwise specified on the Drawing, Purchase Order or Customer Specifications

Customer Service:
Connie Guill, 303.904.6131

Estimator:
Todd Thompson, 303-904-6116

Account Executive:
Jeff Eddy, 480-433-1353

THIS OFFER IS EXPRESSLY CONDITIONED UPON CUSTOMER'S ASSENT TO THE TERMS OF THIS QUOTATION TO VIASYSTEMS' TERMS AND CONDITIONS OF SELLER : www.viasystems.com/tandcseller.pdf

Additional Terms

1. This Quotation is valid for 45 days.
2. If this Quotation is "budgetary" then it is not a final offer to sell.
3. If this Quotation is for Quick Turn Around ("QTA"), then it is subject to upon availability of material.
4. Lead Time is based on working days and on material availability unless otherwise stated.
5. Set-up, E-Test, and additional Non-Recurring Expenses ("NRE") are one-time charges unless otherwise noted.
6. This Quotation is in U.S. Dollars unless otherwise noted. Prices are subject to adjustment based upon currency fluctuations.
7. Prices may change based upon submission of final electronic data and specifications.
8. Prices are based upon Estimated Annual Units ("EAU") listed above and may increase if actual order amount varies from EAU.
9. Prices are based on a Minimum Order Quantity ("MOQ") and may increase if the actual order amount is less than the MOQ.
10. This Quotation is based on certain specific economic factors including the price of materials as of the date hereof. To the extent that Viasystems experiences a change in any of the economic factors upon which this Quotation is based, Viasystems reserves the right to change the prices set forth in this Quotation.
11. Final decision on design and the selection of materials is the responsibility of Customer.
12. Viasystems considers its pricing to be a trade secret and confidential. By soliciting this Quotation, Customer hereby agrees to maintain the confidentiality of Viasystems' pricing.